

### Features

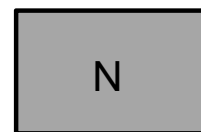
- ◇ 350W (8x20us) Peak Pulse Power
- ◇ Low Clamping Voltage
- ◇ SOD-323 Package
- ◇ RoHS Compliant
- ◇ Matte Tin Lead finish (Pb-Free)
- ◇ Protect One I/O or Power Line
- ◇ Meet IEC61000-4-2 Level 4:  
Contact Discharge > 30 kV  
Air Discharge > 30 kV

### Mechanical Data

Package: SOD-323  
Lead Finish: Lead Free  
UL Flammability Classification Rating 94V-0

### Applications

Smart Phones  
Laptop Computers  
Portable Electronics



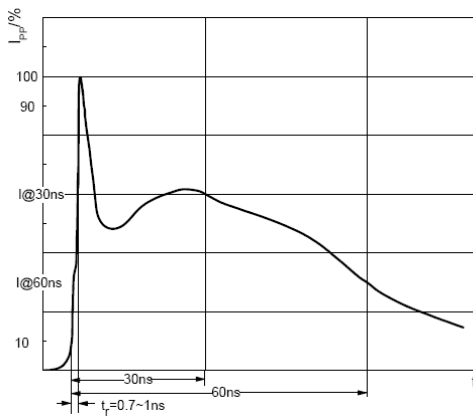
SOD-323

### Absolute Maximum Rating

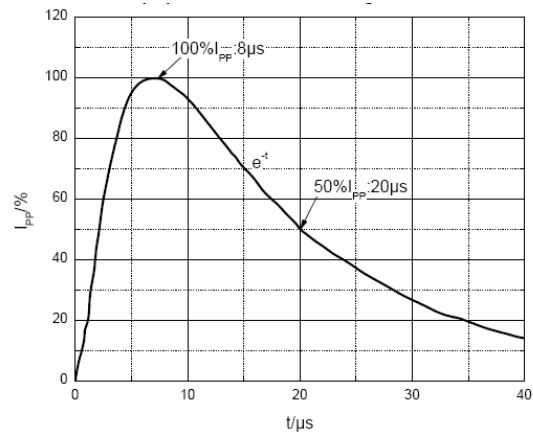
Symbol	Parameter	Value	Unit
TJ	Junction Temperature	-55 to +150	°C
TSTG	Storage Temperature	-55 to +150	°C
Ipp Max	Maximum Peak Pulse Current	10	A
PPK	Peak Pulse Power	350	W

## Electrical Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VRWM	Reverse Working Peak Voltage				18	V
VBR	Reverse Breakdown Voltage	$I_T = 1\text{mA}$	20	21	23	V
IR	Reverse Leakage Current	$VRWM = 18\text{V}$			0.5	$\mu\text{A}$
VC	Clamping Voltage	$I_{PP} = 1\text{A} (8/20\mu\text{s})$			27	V
VC	Clamping Voltage	$I_{PP} = 10\text{A} (8/20\mu\text{s})$			35	V
Ipp	Peak Pulse Current	$t_p = 8/20\mu\text{s}$			10	A
CJ	Capacitance	$VR = 0\text{V}, f = 1\text{MHz}$		42	82	pF



ESD pulse waveform according to IEC61000-4-2

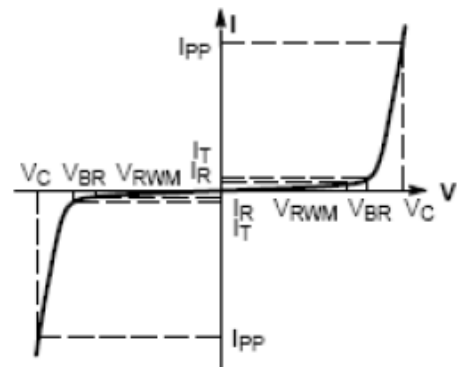


8/20 $\mu\text{s}$  pulse waveform according to IEC 61000-4-5

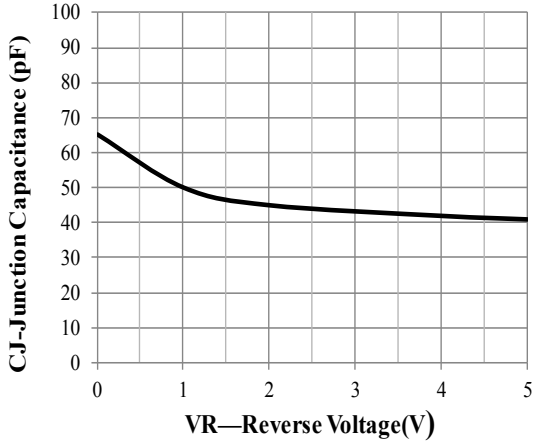
## Electrical Parameters (TA = 25°C unless otherwise noted)

Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current

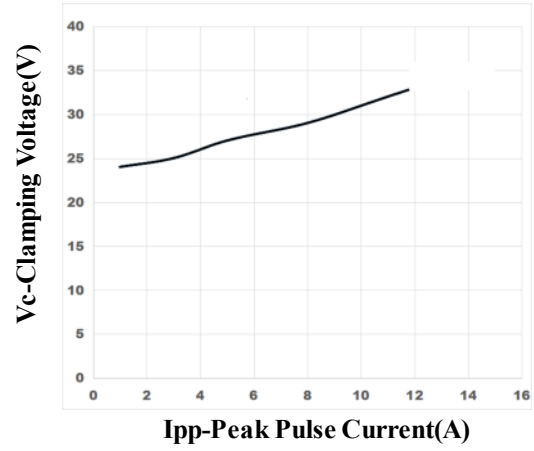
Note: 8/20 $\mu\text{s}$  pulse waveform.



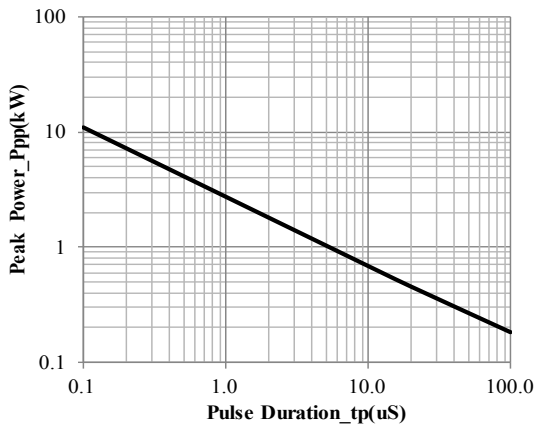
**RATING AND CHARACTERISTIC CURVES**



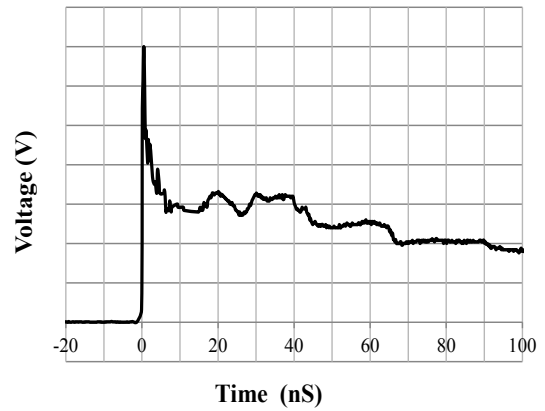
**Junction Capacitance vs. Reverse Voltage**



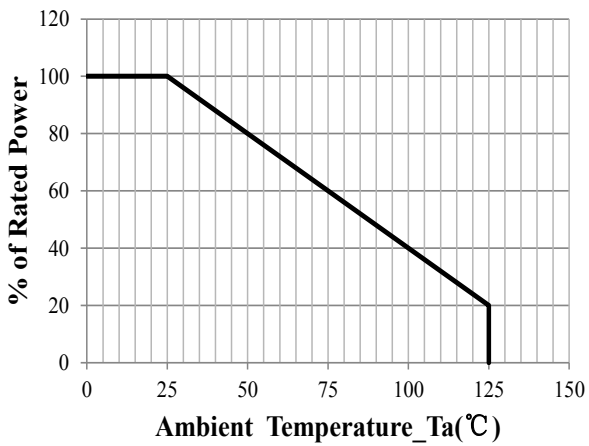
**Clamping Voltage vs. Peak Pulse Current**



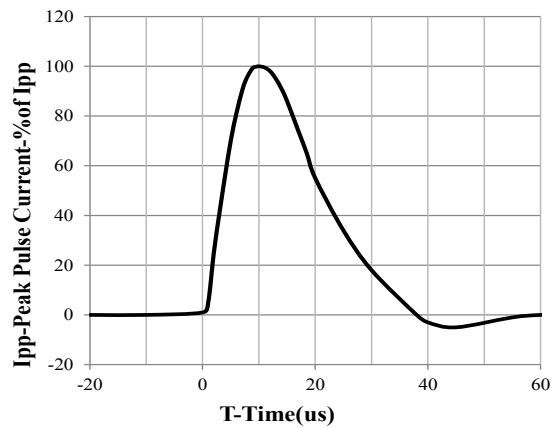
**Peak Pulse Power vs. Pulse Time**



**IEC61000-4-2 Pulse Waveform**



**Power Derating Curve**



**8 X 20us Pulse Waveform**

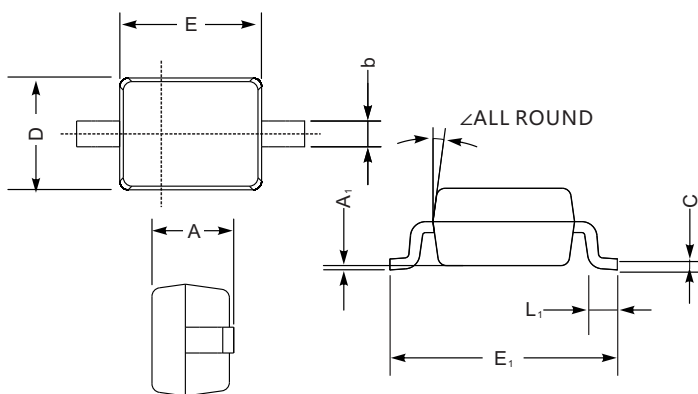
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature( $T_L$ )(Liquid us)	+217°C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_P$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_P$ )		8 min. Max
Do not exceed		+260°C



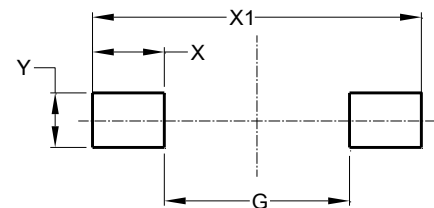
Package Dimensions & Suggested Pad Layout

SOD323



SOD-323 mechanical data

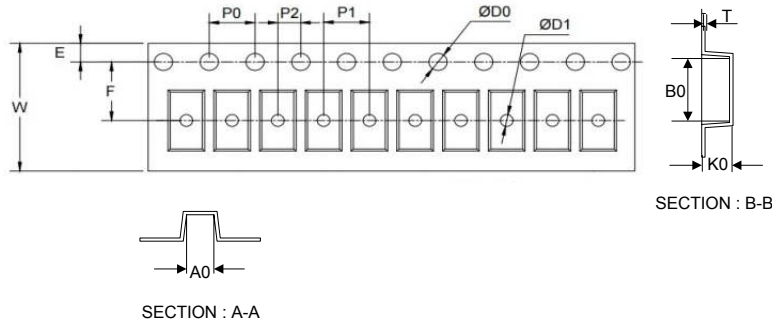
UNIT		A	C	D	E	E <sub>1</sub>	b	L <sub>1</sub>	A <sub>1</sub>	∠
mm	max	1.1	0.15	1.4	1.8	2.75	0.4	0.45	0.2	9°
	min	0.8	0.08	1.2	1.4	2.55	0.25	0.2	—	
mil	max	43	5.9	55	70	108	16	16	8	
	min	32	3.1	47	63	100	9.8	7.9	—	



Dimensions	Value (in mm)
G	1.40
X	1.20
X1	3.80
Y	1.00

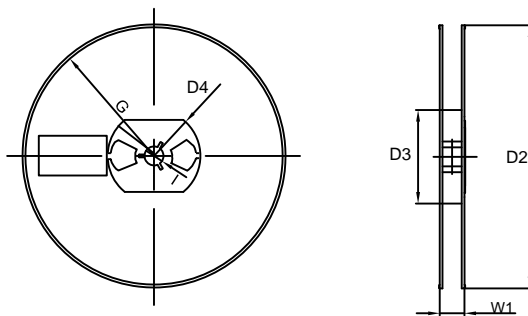
Tape & reel specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.20
P1	4.00±0.20
P2	2.00±0.20
D0	1.55±0.20
D1	1.00±0.20
E	1.55±0.25
F	3.60±0.20
W	8.00±0.20
A0	2.00±0.20
B0	3.25±0.20
K0	1.35±0.20
T	0.23±0.10
D2	177.0±5.0
D3	55Min.
D4	R24.6±2.0
G	R82.0±2.0
I	13.0±2.0
W1	10.20±3.0

7" Reel



Quantity: 3000PCS